

EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L3	350	425/128.ccls.	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT	OR	OFF	2009/01/08 11:52
L4	17327	257/787.ccls. 257/ e21.502.ccls. 257/ e21.504.ccls. 257/ e21.705.ccls. 257/ e23.116.ccls. 257/ e23.125.ccls. 438/108. ccls. 438/124.ccls. 438/126.ccls. 438/127.ccls. 156/500.ccls. 425/117.ccls. 425/125.ccls. 425/128.ccls.	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT	OR	OFF	2009/01/08 11:54
L5	372	L4 and ((encapsulat \$6 mold\$6 packag\$6 resin plastic epoxy) same (semiconductor silicon die dice chip wafer fragment integrated ic component) same (carrier substrate board pwb pcb base) same (cavity feed\$6 assembl\$6) same (edge project\$6) same (movable displac \$6 support receiv\$6 force part))	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT	OR	ON	2009/01/08 11:54
L6	408	(encapsulat\$6 mold \$6 packag\$6 resin plastic epoxy) same (semiconductor silicon die dice chip wafer fragment integrated ic component) same (carrier substrate board pwb pcb base) same (cavity space open\$6) same (feed \$6 assembl\$6) same (edge project\$6)	US-PGPUB; USPAT	OR	ON	2009/01/08 12:07

		same (mov\$6 displac \$6 adjust\$6) same (support receiv\$6 force part)				
L7	226	(encapsulat\$6 mold \$6 packag\$6 resin plastic epoxy) and (semiconductor silicon die dice chip wafer fragment integrated ic component) and (carrier substrate board pwb pcb base) and (cavity space open\$6) and (feed\$6 assembl\$6) and (edge project\$6) and (mov\$6 displac\$6 adjust\$6) and (support receiv\$6 force part)	FPFRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/01/08 12:13

1/ 8/ 09 12:19:07 PM

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